Bipolar Power Transistors

PNP Silicon

Features

Collector – Emitter Sustaining Voltage –

$$V_{CEO(sus)} = 40 \text{ Vdc (Min)} @ I_C = 10 \text{ mAdc}$$

• High DC Current Gain -

$$h_{FE}$$
 = 200 (Min) @ I_C = 1.0 Adc
= 100 (Min) @ I_C = 3.0 Adc

• Low Collector -Emitter Saturation Voltage -

$$V_{CE(sat)} = 0.200 \text{ Vdc (Max)} @ I_C = 1.0 \text{ Adc}$$

= 0.500 Vdc (Max) @ I_C = 3.0 Adc

- SOT-223 Surface Mount Packaging
- Epoxy Meets UL 94, V-0 @ 0.125 in
- ESD Ratings:
 - Human Body Model, 3B; > 8000 V
 - Machine Model, C; > 400 V
- AEC-Q101 Qualified and PPAP Capable
- NJV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant*



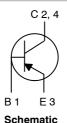
ON Semiconductor®

http://onsemi.com

PNP TRANSISTOR 3.0 AMPERES 40 VOLTS, 2.0 WATTS



SOT-223 CASE 318E STYLE 1



MARKING DIAGRAM



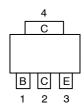
A = Assembly Location

' Year

W = Work Week

4030P = Specific Device Code ■ Pb-Free Package

PIN ASSIGNMENT



Top View Pinout

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Collector-Emitter Voltage	V _{CEO}	40	Vdc
Collector-Base Voltage	V _{CB}	40	Vdc
Emitter-Base Voltage	V _{EB}	6.0	Vdc
Base Current - Continuous	I _B	1.0	Adc
Collector Current Continuous Peak	I _C	3.0 5.0	Adc
Total Power Dissipation Total P_D @ T_A = 25°C mounted on 1" sq. (645 sq. mm) Collector pad on FR-4 bd material Total P_D @ T_A = 25°C mounted on 0.012" sq. (7.6 sq. mm) Collector pad on FR-4 bd material	P _D	2.0 0.80	W
Operating and Storage Junction Temperature Range	T _J , T _{stg}	-55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Case Junction-to-Ambient on 1" sq. (645 sq. mm) Collector pad on FR-4 bd material Junction-to-Ambient on 0.012" sq. (7.6 sq. mm) Collector pad on FR-4 bd material	$egin{array}{c} R_{ hetaJA} \ R_{ hetaJA} \end{array}$	64 155	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 5 seconds	TL	260	°C

ORDERING INFORMATION

Device	Package	Shipping [†]
NJT4030PT1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NJV4030PT1G	SOT-223 (Pb-Free)	1,000 / Tape & Reel
NJT4030PT3G	SOT-223 (Pb-Free)	4,000 / Tape & Reel
NJV4030PT3G	SOT-223 (Pb-Free)	4,000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_C = 25^{\circ}C$ unless otherwise noted)

, -2	,				
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
Collector-Emitter Sustaining Voltage (I _C = 10 mAdc, I _B = 0 Adc)	V _{CEO(sus)}	40	-	-	Vdc
Emitter-Base Voltage (I _E = 50 μAdc, I _C = 0 Adc)	V _{EBO}	6.0	-	-	Vdc
Collector Cutoff Current (V _{CB} = 40 Vdc)	I _{CBO}	-	-	100	nAdc
Emitter Cutoff Current (V _{BE} = 6.0 Vdc)	I _{EBO}	-	-	100	nAdc
ON CHARACTERISTICS (Note 1)				•	
Collector–Emitter Saturation Voltage ($I_C = 0.5 \text{ Adc}$, $I_B = 5.0 \text{ mAdc}$) ($I_C = 1.0 \text{ Adc}$, $I_B = 10 \text{ mAdc}$) ($I_C = 3.0 \text{ Adc}$, $I_B = 0.3 \text{ Adc}$)	V _{CE(sat)}	- - -	- - -	0.150 0.200 0.500	Vdc
Base–Emitter Saturation Voltage ($I_C = 1.0 \text{ Adc}$, $I_B = 0.1 \text{ Adc}$)	V _{BE(sat)}	-	-	1.0	Vdc
Base–Emitter On Voltage (I _C = 1.0 Adc, V _{CE} = 2.0 Vdc)	V _{BE(on)}	-	-	1.0	Vdc
DC Current Gain $(I_C = 0.5 \text{ Adc}, V_{CE} = 1.0 \text{ Vdc})$ $(I_C = 1.0 \text{ Adc}, V_{CE} = 1.0 \text{ Vdc})$ $(I_C = 3.0 \text{ Adc}, V_{CE} = 1.0 \text{ Vdc})$	h _{FE}	220 200 100	- - -	- 400 -	-
DYNAMIC CHARACTERISTICS					
Output Capacitance (V _{CB} = 10 Vdc, f = 1.0 MHz)	C _{ob}	-	40	-	pF
Input Capacitance (V _{EB} = 5.0 Vdc, f = 1.0 MHz)	C _{ib}	-	130	-	pF
Current–Gain – Bandwidth Product (Note 2) (I _C = 500 mA, V _{CE} = 10 V, F _{test} = 1.0 MHz)	f _T	_	160	_	MHz

^{1.} Pulse Test: Pulse Width ≤[300 μs, Duty Cycle ≤ 2%.

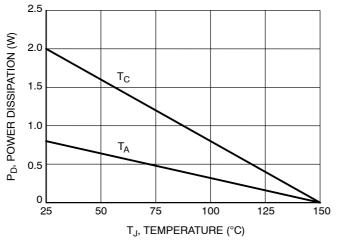


Figure 1. Power Derating

^{2.} $f_T = |h_{FE}| \cdot f_{test}$

TYPICAL CHARACTERISTICS

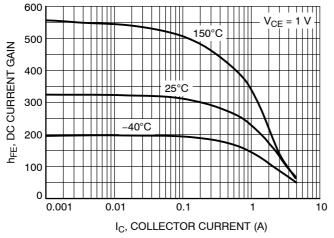


Figure 2. DC Current Gain

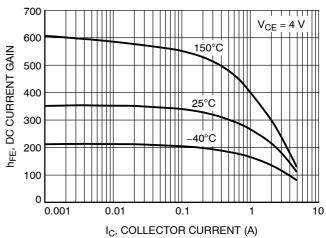
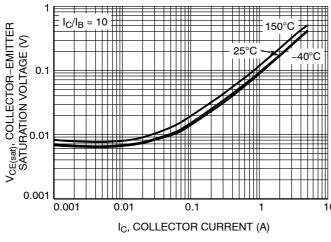


Figure 3. DC Current Gain





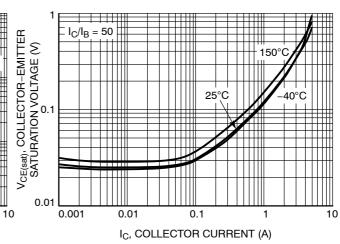


Figure 5. Collector-Emitter Saturation Voltage

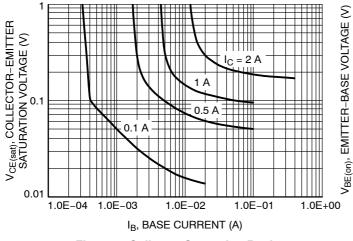


Figure 6. Collector Saturation Region

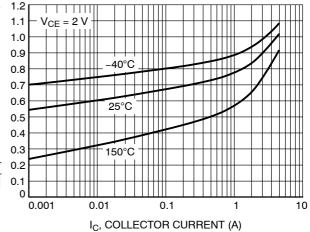


Figure 7. V_{BE(on)} Voltage

TYPICAL CHARACTERISTICS

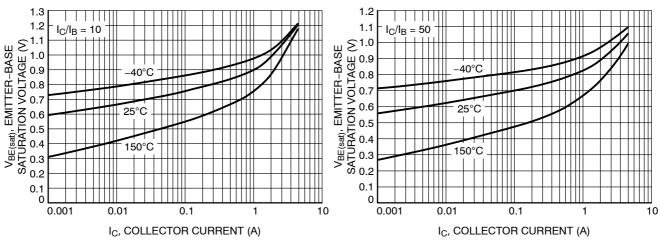


Figure 8. Base-Emitter Saturation Voltage

Figure 9. Base-Emitter Saturation Voltage

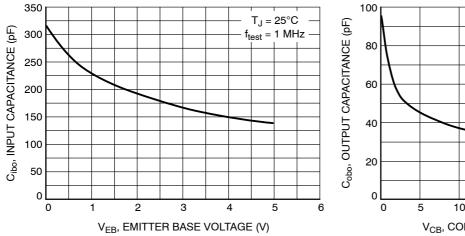


Figure 10. Input Capacitance

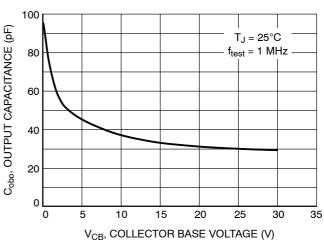


Figure 11. Output Capacitance

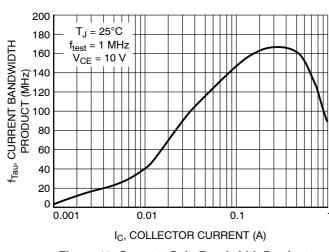


Figure 12. Current-Gain Bandwidth Product

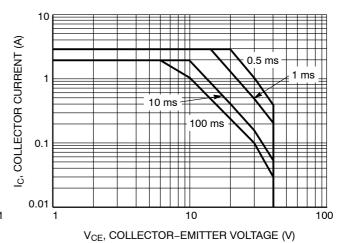
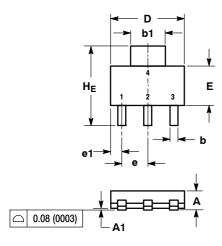
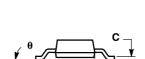


Figure 13. Safe Operating Area

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 ISSUE N





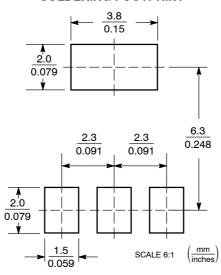
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- CONTROLLING DIMENSION: INCH.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	1.50	1.63	1.75	0.060	0.064	0.068	
A1	0.02	0.06	0.10	0.001	0.002	0.004	
b	0.60	0.75	0.89	0.024	0.030	0.035	
b1	2.90	3.06	3.20	0.115	0.121	0.126	
С	0.24	0.29	0.35	0.009	0.012	0.014	
D	6.30	6.50	6.70	0.249	0.256	0.263	
E	3.30	3.50	3.70	0.130	0.138	0.145	
е	2.20	2.30	2.40	0.087	0.091	0.094	
e1	0.85	0.94	1.05	0.033	0.037	0.041	
L	0.20			0.008			
L1	1.50	1.75	2.00	0.060	0.069	0.078	
HE	6.70	7.00	7.30	0.264	0.276	0.287	
θ	0°	_	10°	0°	_	10°	

STYLE 1: PIN 1. BASE

- 2. COLLECTOR 3. EMITTER
- 4 COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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